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MacDermid Alpha Releases Complete Semi-Additive Process for IC Substrates and Panel Level Packaging: Systek SAP

(Waterbury, CT USA) – June 4th, 2020 – MacDermid Alpha Electronics Solutions, a global leader in specialty materials for electronics, announces the release of Systek SAP.

The MacDermid Alpha Systek SAP is a family of high-performance build-up processes for IC substrate RDL that provide multiple process flows for different materials as well as revolutionary technology innovations in the desmear, conditioning, activation and metallization steps. With Systek SAP, new design possibilities in IC substrate manufacturing of high-density circuitry are now available for fine-line, ultra fine-line and flex materials. Systek SAP starts with a four-step desmear process that can be calibrated to optimally prepare multiple substrate materials, imparting minimal roughness while ensuring clean via side walls and copper target pads. The subsequent conditioner process ensures adsorption of the palladium catalyst into the substrate. The Systek SAP copper metallization process includes an ionic palladium activation system, a zero-stress electroless copper metallization process, and an optional anti-tarnish. Together, the new technologies in the Systek SAP family of semi-additive processes provide substrate manufacturers an easy-to-use toolset for creating RDL with dimensions down to 5/5 micron line/space for very high-density packaging.

“The Systek SAP process represents the pinnacle of years of experience in many aspects of high technology circuit metallization. IC substrate fabricators expanding capacity into new designs are excited about the systems innovations that they can take advantage of in manufacturing reduced roughness, high-density packaging designs for next-gen devices.” said Bill Bowerman, Director of Primary Metallization, Circuitry Solutions.

For more information on Systek SAP, please visit www.MacDermidAlpha.com

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